

## <u>Technology/News Roundup</u>

## **Custom Substrates White Paper Now Available**

Substrates provide the mechanical strength and electrical connectivity for the complex circuits inside semiconductor packages. QP Technologies provides custom substrate development services to fill technological gaps that standard packages cannot accommodate. Our latest white paper outlines our process for developing substrates to meet customer needs, including examples from our work with Mixed-Signal Devices (MSD). To download the white paper and read more about our expertise in working with a wide variety of custom substrates, click <a href="here.">here.</a>

# **QP Technologies Continues to Grow Die Preparation Business**

In June, QP Technologies announced that we're continuing to expand our die and wafer preparation business, recently adding a state-of-the-art dicing saw to our manufacturing line. The Disco DFD6362, our fully automated dicing system, enables quick, efficient processing of a full 300mm wafer cassette – in turn, helping to improve turnaround time and productivity for customer projects. We also recently added to our assembly offerings, installing another Royce Autoplacer MP 300, ensuring precise, mechanized die pick-and-place during assembly.

With customers leveraging larger wafers to build their devices and reshoring of semiconductor manufacturing surging – thanks to U.S. CHIPS Act funding – we recognize the importance of making sure we're fully equipped to meet these demands. Chipmakers will be seeking U.S.-based companies that can deliver wafer prep, packaging and assembly, and QP Technologies is well positioned to stake out a stronger position in this new ecosystem.



## Employee Spotlight

# Matt Hansen, VP, Sales and Marketing, QP Technologies

Matt Hansen joined us in early 2024 as director of sales and business development for Promex Industries, bringing with him more than two decades of tech industry experience. With our July 1<sup>st</sup> reorganization, we implemented a number of promotions and role changes within both Promex and QP Technologies. One of these changes was to name Matt vice president of sales and marketing for QP Technologies – a position previously held by Rosie Medina, who was promoted to sr. vice president of sales and marketing for Promex. In their new roles, Matt and Rosie will be fully dedicated to QP Tech and Promex, respectively.

Matt knew the company's reputation for engineering excellence, and welcomed the chance to work with Rosie again. While also known for its skilled engineers, QP Technologies' business challenges differ from Promex's. The opportunity to focus on sales and marketing for QP Tech is one that Matt is looking forward to, drawing on his background and experience in the military-aerospace (mil-aero) and microelectromechanical systems (MEMS) and sensors markets. Matt will be working to attract customers in these markets to QP Tech's quickturn packaging, assembly, wafer preparation and substrate development solutions.

### **Recent Events**

- **Sensors Converge:** Promex and QP Technologies joined forces at Sensors Converge in Santa Clara to showcase our ability to help customers with manufacturing requirements from low-volume quick turns to complex assembly programs in development to production. It was nice to see our customers at this show and to establish many new relationships in the sensors community. Dave Fromm's conference session, "Design Considerations for Building Heterogeneously Integrated Sensor Devices," was well received, enabling us to share our expertise with this key audience.
- International Microwave Symposium (IMS): QP Technologies had another successful showing at IEEE MTT-S IMS in Washington, D.C., a longtime staple event for us. At IMS, we had an opportunity to talk with attendees about our packaging and assembly capabilities for RF, power, and military-aerospace applications.
- **Electronic Components & Technology Conference (ECTC):** We were pleased to participate at IEEE ECTC in Denver for the first time. With a record number of attendees, our sales team was quite active in the QP Technologies booth. Heterogeneous

integration seemed to be the key topic, with many customers requesting information on our custom substrate fabrication and design services. We look forward to pursuing these opportunities.

## Recent Media Coverage

- Semiconductor Engineering:
  - In May, Greg Haley published an article looking at the status of developing and implementing glass substrates for advanced packaging. The piece included a quote from Promex COO Dave Fromm. Read the full article here.
  - Greg also wrote in March about the rise of silicon photonics manufacturing. Dave Fromm was quoted in this piece commenting on the CTE (coefficient of thermal expansion) challenges associated with photonics circuits. Read the full article <a href="here">here</a>.
  - In April, Anne Meixner posted an in-depth article on chiplets and what companies need to consider when combining chiplets from different companies in one package. Promex CEO Dick Otte commented on the challenges this presents with respect to control and tolerance. Read the full article <a href="here">here</a>.

#### ASSEMBLY Audible:

 In April, Jennifer Pierce interviewed Promex COO Dave Fromm on an episode of this podcast. They discussed Promex's partnership with medical and biotech companies throughout the assembly process of medical devices, from prototypes to production. Listen to the full episode <a href="here">here</a>.

# <u>Upcoming Events</u>

- Promex
  - ADLM 2024 July 28-Aug. 1, Chicago, IL Exhibitor, Booth 114
  - MEDevice Silicon Valley November 20-21, Santa Clara, CA Exhibitor, Booth 1443
  - o Annual Open House November 20 in Santa Clara, CA

#### QP Technologies

- European Microwave Week September 24-26, Paris, France Exhibitor, Booth
  350C
- iMAPS International Symposium on Microelectronics October 1-2, Boston, MA Exhibitor
- MEMS & Imaging Sensors Summit November 14-15, Munich, Germany Exhibitor, Booth 1

#### **About Us**

QP Technologies is a leading provider of microelectronic packaging and assembly, wafer preparation, and substrate design and development services. We leverage proven technologies developed by our skilled staff, and we work closely with you to get your products to market quickly, with the highest quality prototype and production volumes.



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